Amendments to the Specification:

Please replace paragraph [0003] with the following amended paragraph:

[0003] Japanese Unexamined Patent Publication (Kokai) No. ~~2001~~ 2000-323848 discloses an electronic control device that has been used. In this electronic control device, a major portion working as the electronic control device 1 is accommodated in a connector-integrated resin casing 2 with which a connector casing is integrally molded. A data-receiving connector and a power supply connector are disposed by being grouped into one on the side surface of the connector-integrated resin casing 2. This enables the electric connection between the electronic control device and the external electronic part to be accomplished from one side of the unit.

Please replace paragraph [0064] with the following amended paragraph:

[0064] When the casing body 41 is formed, the lead conductors 46 are formed integrally therewith as the data-receiving connector together with the data-receiving connector terminals 43. Described above was the case of the lead conductors 46 being continuous to the control connector terminals 43. Further, the electric connection between the power supply connector terminals 45 and the electronic circuit on the control circuit substrate 31, too, is accomplished relying upon basically the same constitution as the lead conductors 46 continuous to the data-receiving connector terminals 43. The

only difference in the constitution is that, in the case of the power circuit unit, the lead conductors have a larger thickness than that of the control circuit unit.

~~Mounting the electronic control device on the wall of the transmission~~

Please replace paragraph [0077] with the following amended paragraph:

[0077] Even without forming the stepped portion on the wall TM of the transmission, the two mounting protrusions may be so formed as to hold a portion of the body of the transmission.

~~Radiating the heat of the electronic parts on the control circuit substrate~~

Please replace paragraph [0083] with the following amended paragraph:

[0083] Instead of using the belt like heat-conducting member 56 that is integrally molded, therefore, there is used a heat-conducting metal plate 59 made of copper that is separately formed as shown in Fig. 10. The metal plate 59 is provided with a recessed portion that is formed by draw working to accommodate the electronic part D as well as to reinforce the strength. In mounting the control substrate 31 on the support members 55-1 to 55-4, the metal plate 59 is secured being held between the

control circuit substrate 31 and the support members 55-1 to 55-4. Upon securing the metal plate 59, the surface of the electronic part D comes into contact with the recessed metallic portion; i.e., heat of the electronic part D is efficiently collected and is transmitted to the support members and heat of the electronic part D is radiated in an improved manner.

~~[~~Modified example of contact between the metal substrate and the wall of the transmission~~]~~